Qualification of an Alternate Adhesive Material and Molding Compound for Select LFCSP Packages

Qualification Plan Summary for 7x7 LFCSP

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**EXPECTED COMPLETION DATE**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 77	Jan 2023
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	Jan 2023
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	1 x 77	Jan 2023
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC *JESD22-A118*	3 x 77	Jan 2023
Field Induced Charged Device Model Electrostatic Discharge (FICDM-ESD)	JEDEC *JS-002-2018*	3/Voltage	Jan 2023

* Preconditioned per JEDEC/IPC J-STD-020.